

Page 6, line 16, change "Electrically" to --Thermally--.

CLAIMS:

Cancel claims 8-10, Amend Claims 1, 6, 7, 11, and 15-19 as follows:

1. (Amended) A semiconductor chip package comprising:
- a ball grid array substrate panel having top and bottom surfaces, said bottom surface having a plurality of solder balls attached thereon;
 - at least one semiconductor chip being mounted substantially in the center of said top surface of said substrate panel;
 - a plurality of contact pads formed on said top surface of said substrate panel, each of said contact pads being located near a corner of said semiconductor chip; and
 - a heat slug having a top plate covering said semiconductor chip and a plurality of flanges extending down to said substrate panel, said top plate having a plurality of hollow cylindrical contact bodies each having a flat bottom for providing close contact with a corresponding contact pad and bonding said heat slug to said substrate panel; [said top plate being bonded to said semiconductor chip by means of a first adhesive material, and said heat slug being connected to said contact pads on said substrate panel by means of a second adhesive material.]
 - wherein said top plate is bonded to said semiconductor chip by means of a first adhesive material, and said heat slug is bonded to said contact pads on said substrate panel by means of a second adhesive material.

6. (Amended) The semiconductor chip package according to claim 1, said heat slug being thermally conductive [further comprising a plurality of contact bodies for